

Dual P-Channel Enhancement Mode Power MOSFET

Description

The HM4843 uses advanced trench technology to provide excellent $R_{DS(ON)}$, This device is suitable for use as a load switch and battery protection applications.

General Features

• $V_{DS} = -40V, I_{D} = -5.0A$

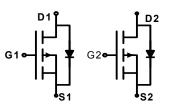
 $R_{DS(ON)}$ < 126m Ω @ V_{GS} =-4.5V

 $R_{DS(ON)}$ < 85m Ω @ V_{GS} =-10V

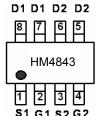
- High power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- Battery applications
- Load switch



Schematic diagram



Marking and pin Assignment



SOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HM4843	HM4843	SOP-8	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-40	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	-5.0	Α
Drain Current-Pulsed (Note 1)	I _{DM}	-20	Α
Maximum Power Dissipation	P _D	2.0	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2) R _{BJA} 62.5
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Electrical Characteristics (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-40	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-40V,V _{GS} =0V	-	-	-1	μΑ



Parameter	Symbol	Condition	Min	Тур	Max	Unit
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)			•	•		•
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =-250μA		-1.5	-3	V
Danie Course On Otata Basista	D	V _{GS} =-10V, I _D =-5A -		73	85	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-4A -		98	126	mΩ
Forward Transconductance	g fs	V _{DS} =-5V,I _D =-4.1A	10	-	-	S
Dynamic Characteristics (Note4)			•	•		•
Input Capacitance	C _{lss}	\/ - 20\/\/ -0\/	-	650	-	PF
Output Capacitance	C _{oss}	V _{DS} =-20V,V _{GS} =0V, F=1.0MHz	-	90	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.000m2	-	70	-	PF
Switching Characteristics (Note 4)	·					
Turn-on Delay Time	t _{d(on)}		-	9	-	nS
Turn-on Rise Time	t _r	V_{DD} =-20 V , R_L =2 Ω	-	8	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10 V , R_{GEN} =3 Ω	-	28	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Qg	\/ = 20\/ = 2.14	-	14	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =-20V,I _D =-3.1A, V _{GS} =-10V	-	2.9	-	nC
Gate-Drain Charge	Q_{gd}	VGS10V	-	3.8	-	nC
Drain-Source Diode Characteristics	·		•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-2.5A	-	8.0	1.2	V
Diode Forward Current (Note 2)	Is		-	-	-5.3	Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

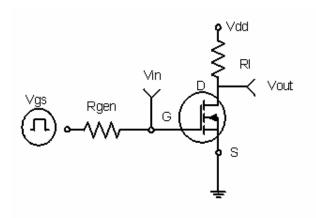


Figure 1:Switching Test Circuit

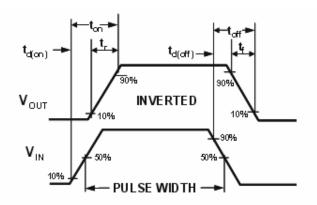
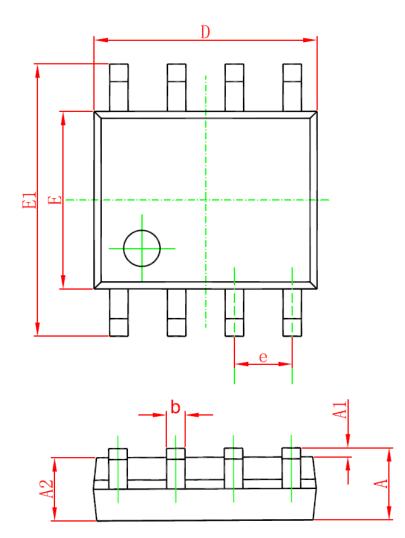
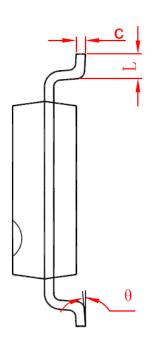


Figure 2:Switching Waveforms



SOP8 PACKAGE OUTLINE DIMENSIONS





Comb a l	Dimensions In	n Millimeters	Dimensions In Inches			
Symbol	Min	Max	Min	Max		
А	1. 350	1. 750	0. 053	0.069		
A1	0. 100	0. 250	0. 004	0.010		
A2	1. 350	1. 550	0. 053	0. 061		
b	0. 330	0. 510	0. 013	0. 020		
С	0. 170	0. 250	0. 006	0.010		
D	4. 700	5. 100	0. 185	0. 200		
Е	3.800	4. 000	0. 150	0. 157		
E1	5. 800	6. 200	0. 228	0. 244		
е	1. 270	(BSC)	0. 050	50 (BSC)		
L	0. 400	1. 270	0. 016	0.050		
θ	0°	8°	0°	8°		

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